

Technical Data Sheet

EverTherm CS series is a composite material which offers extremely high thermal conductivity, low density and good durability. Carbon fiber is an anisotropic and offering a very high level of thermal conductivity in the Z axis. This silica gel sheet is very soft and well compressed, it is used to fill the interface of two substrates, ensuring air from the interface is discharged, and heat conduction dramatically improved. Thermal conductivity @ 20.0W/M.K



Material Properties

- High thermal conductivity
- Excellent flame retardant
- Good flexibility and high compression ratio

Adhesive optional:

- -A1 equals single-sided adhesive;
- -A2 equals double-sided adhesive

Applications

- ✓ Semiconductor heat sink
- ✓ Electric Vehicle (EV) Batteries
- Communication & power devises & modules
- ✓ LED lighting equipment
- ✓ Electronic components like: LEDs, CPUs, MOS • Mobiles, Laptops, Tablets



EVCSF20		
Color	Black	Visual
Thickness	0.50 ~ 20.0mm	ASTM D374
Metal	Silicone rubbei	***
Filler	Carbon	***
Density	2.9g/cm3	ASTM D792
Thermal Conductivity	20.0W/m-K	ASTM D5470
Hardness (Shore 00)	40~90	ASTM D2240
Normal Hardness (Shore 00)	40/60±5	ASTM D2240
Elongation	30%	ASTM D412
Tensile Strength	30psi	ASTM D412
Thermal Resistance (1mm,@40psi)	0.09 *in2/W	ASTM D5470
Operating Temperature(℃)	-50~ 160	ASTM D1329
REACH	PASS	EN14

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

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Note: The information provided herein is accurate at time of publication. It is the responsibility of the end-user to confirm compliance to their application. All test data is typical. Therefore, these recommendations and data are for reference only and not as a product warranty.